



Holes shown for component mounting, used for reference only.

2	RTIH-1	
Q'TY./UNIT	MODEL USED ON	ASS'Y. NO.
SCALE 2:1	CODE	
THE CONTENTS OF THIS DRAWING ARE THE EXCLUSIVE PROPERTY OF THE TECHNICAL MATERIEL CORP. ITS UNAUTHORIZED USE OR REPRODUCTION IN WHOLE OR IN PART IS STRICTLY FORBIDDEN.		

NOTES

A4377

REVISIONS					
SYM	DESCRIPTION	DATE	E.M.N. NO.	DRAFT	CHKD APPD
X	EXPERIMENTAL RELEASE	6.10.66	--	WFW	
X ₁	CC100-6 ADDED	6.16.66	--	WFW	JK
X	ORIGINAL RELEASE FOR PRODUCTION	7.19.66	Q	PMG	

ASSEMBLY NOTES

1. TO MOUNT COMPONENTS INSERT LEAD THROUGH PLATED-THRU HOLES.
2. APPLY HEAT AND SOLDER TO LEAD & FOIL. CAUTION: TO MUCH HEAT WILL CAUSE THE FOIL TO SEPARATE FROM THE BOARD.
3. CLEAN AND INSPECT PER S676.
4. FUNGUS PROOFING PER TMC SPECIFICATION S113.
5. BOARD EDGES MUST BE CLEARED OF SOLDER. APPROXIMATELY 3/16 FROM EDGES.

REF. CK1157

REQ'D.	ITEM	PART NUMBER	DESCRIPTION	SYMBOL
X	5	BS100	SOLDER, TIN ALLOY	
8	4	CC100-11	CAP, FIXED	C1 THRU C8
8	3	NW108-28	AND GATE	Z9 THRU Z16
8	2	NW107-4X	FLIP FLOP	Z1 THRU Z8
1	1	PC258	PRINTED CIRCUIT BOARD	

EATON LIST OF MATERIAL					
MATERIAL			THE TECHNICAL MATERIEL CORP. MAMARONECK, NEW YORK		
FINISH			TITLE ASS'Y PRINTED CIRCUIT BD (MEMORY/GATING CIRCUIT)		
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES AND INCLUDE CHEMICALLY APPLIED OR PLATED FINISHES			DRAWN WFW	DATE 6.9.66	FINAL APPROVAL F. Blato M. May
DECIMALS .X ± .05 .XX ± .01 .XXX ± .005			CHECKED JK	DATE	7/19/66
FRACTIONS ± 1/64 ANGLES ± 0° 30'			ELECT. DES.	DATE	
TOLERANCES			MECH. DES.	DATE	
			SHEET		REV. LTR.

M/L N. Adl 7-13